



DETAIL A
SCALE 5:1

- NOTES:
1. INTERPRET DRAWING PER ASME Y14.5M-1994.
 2. MATERIAL:
HEATSINK;ALUMINUM 6063 T5 SURFACE TREATMENT WITH BLACK
THERMAL PAD: T725
PUSH PIN: CUSTOMER DESIGNATED PARTS, SUPPLIER IS FREROX ELECTRONICS, SUPPLIER P/N IS MCC-1, COLOR IS BLACK.
 3. ALL EDGES AND CORNERS MUST MEET SAFE HANDLING.
 4. RoHS COMPLIANT AND CERTIFIED.
 5. USE FOR CHASSIS HOLE WITH DIA. 3 TO 3.2 MM.
 6. USE FOR THICKNESS OF CHASSIS AND CHIP WITH 3.8 TO 4.8 MM.

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LOC	-
DIST	-

	A	INITIAL RELEASE	5MAY2008	ERIC	MICD
P	LTR	REVISION RECORD	DATE	DWN	APVD

TYCO PART NO: 5-1961000-0		DWN Eric Han 29JUN2007	MATERIAL See Notes	HEAT TREAT N/A
DIMENSIONS: mm		CHK Mico Yu 29JUN2007	Tyco Electronics Corporation Zhuhai Guangdong	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1.00 1 PLC ± 0.50 2 PLC ± 0.30 3 PLC ± 0.13 4 PLC ± 0.06		APVD Mico Yu 29JUN2007		
ANGLES ± 2° SURFACE TEXTURE		NAME CHIPSET HEATSINK FOR PHILIPS		
SCALE 1:1	SIZE A3	DRAWING NO C-5-1961000-0	SHEET 1 OF 1	REV A

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)